



Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information
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Supplier Information

Company name* onsemi	Company unique ID	Unique ID Authority	Response Date* 2023-06-08
Contact Name Product-Env-Stewards	Title - Contact Product Enviro Compliance	Phone - Contact* NA	Email - Contact* Product-Env-Stewards@onsemi.com
Authorized Representative* Product-Env-Stewards	Title - Representative Product Enviro Compliance	Phone - Representative* NA	Email - Representative* Product-Env-Stewards@onsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
	FSA2267AMUX	Dual SPDT Analog Switch	2023-06-08		CNS	25.8	mg	Each

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)	CU Alloy	1	260 C	30 seconds	3

Comments
level 1 - maximum time at peak temperature during soldering is 10-30 seconds
For more information regarding material composition please refer to page 3

